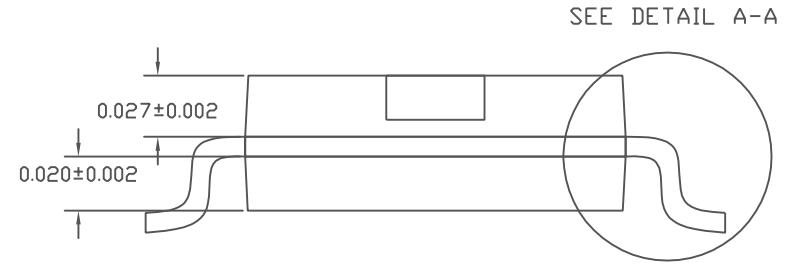
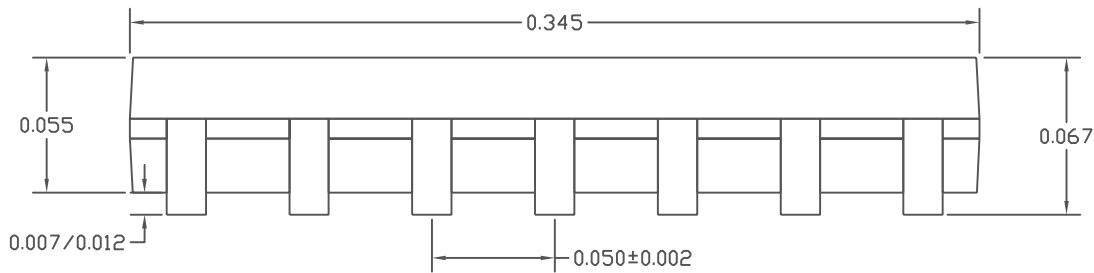
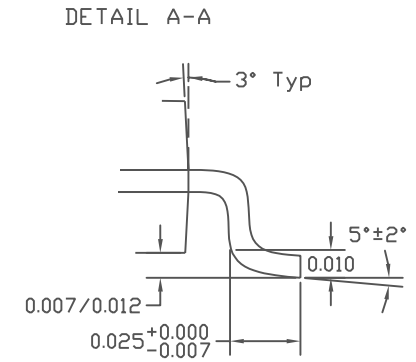
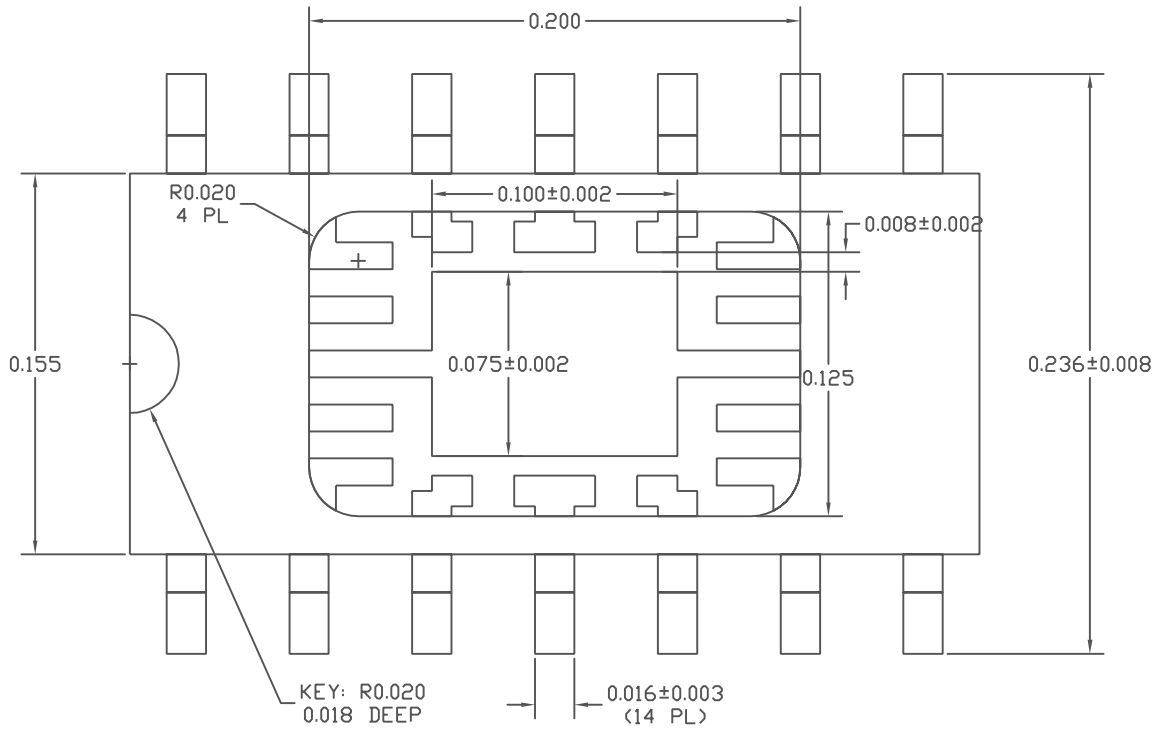


ECN	REV.	DESCRIPTION	DATE	APP'D:
10017	-	INITIAL RELEASE	2/21/01	BF



NOTES:
 BODY : Plastic, Semiconductor Grade
 LEAD FRAME : Copper, Qlin 194
 LEAD FINISH : 50uIN Au, Over 50uIN Ni
 FRAME THICKNESS : 0.008" +/- 0.001"



TITLE: 14 Lead SOIC Open-Pak (0.150" Wide)

MATERIAL: SEE NOTES	SCALE: NONE	DRAWN BY: S.D.
GEN. TOL.: ±0.005	DATE: 11/19/00	APP'D: BF 2/21/01
SSM P/N: PS0141501	DWG. NO.: SOIC14-OP-01	REV.: 1